

**Position available:** Test, inspection, and assembly technician

**Job Description:** The test, inspection, and assembly technician will carry out operations pertaining to prototype assembly and design verification testing of the Company's products including wafers, chips, and assemblies. Responsibilities include support of engineering activities at Hoya Xponent's Monrovia facility and may include inspection, training, auditing and troubleshooting in support of production at off-site/off-shore contract manufacturers and foundries.

**Essential Job Requirements:** The successful candidate will:

1. Conduct and report on detailed wafer-level inspections and testing of III-V wafers for engineering and production
2. Monitor and report on quality of III-V chips against target specification as processed and delivered by contract manufacturer
3. Support engineering and production activities by developing, executing, and documenting inspection, handling, and testing operations for III-V wafer and chips
4. Perform on-site audits, training, and inspections at off-site/off-shore III-V foundry/contract manufacturer
5. Conduct and report on design verification & reliability testing for Hoya Xponent's products, wafers and chips.
6. Maintain, troubleshoot, and support test equipment including test & reliability assessment hardware
7. Monitor and report on yield and failure modes affecting engineering devices and products.
8. Support engineering activities by developing, executing, and documenting inspection, assembly and test operations including submount, module, and board level assembly.

**Education & Experience:** AA degree with 1-2 years experience in optoelectronics device assembly or test.

**Required Skills:**

The ideal candidate will have prior experience and the required manual dexterity to handle fragile III-V wafers and small chips. Require ability to visually track fine details and discovering small defects among many inspected parts. The candidate will have familiarity with optoelectronic test equipment; dexterity for precision alignment and assembly of components; and the ability to learn, understand master new test configurations, assembly processes, as well as possessing excellent communication skills. Familiarity with device opto-electrical testing, manual and automated testing of lasers and photodiodes. Familiarity with wire-bonding: wedge bonding and/or ball-bonding, flip-chip die bonding a plus.

For consideration, please email resumes to [resume@hoyaoptics.com](mailto:resume@hoyaoptics.com) and include "**Test, inspection, and assembly technician**" in the subject line.

**Hoya Xponent is an Equal Opportunity Employer.**

